



Customer Information Notification

201909005I

Issue Date: 21-Nov-2019

Effective Date: 22-Nov-2019

Dear *Emma Tempest*,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP.

For detailed information we invite you to [view this notification online](#)

This notice is NXP Company Proprietary.



Change Category

- | | | | | |
|--|---|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input checked="" type="checkbox"/> Other - Data Sheet OTP Updates and Clarifications | | | |

PF8100-PF8200 Data Sheet Updates Rev 8.0 and 9.0 for Ordering Information and Clarifications

Description

NXP Semiconductors announces data sheet update revisions 8.0 and 9.0 for the PF8100-PF8200 devices associated with this notification. The new data sheet revisions provide updated ordering information and clarifications, including additional details for ISW5LIM specification to ensure compatibility with the i.MX8QM microprocessors specification, and clarification regarding FSOB configuration differences between PF8100 and PF8200 devices. The revision history included in the updated document provides a detailed description of the changes. Changes are summarized below.

Revision 8.0: PF8100_PF8200 Data Sheet Change Summary

1. Add note: "Not recommended for new designs", for part numbers MC33PF8100CCES / MC34PF8100CCEP.
2. Add part numbers MC33PF8100FJES / MC34PF8100FJEP
3. Remove part numbers MC33PF8200DMES / MC33PF8200DNES.

4. Modify OTP Reports for the following parts:

- MC33PF8100EPES / MC34PF8100EPEP
- MC33PF8100EQES / MC34PF8100EQEP
- MC33PF8200DBES
- MC33PF8200DEES
- MC33PF8200ESES

5. Add note: "VSWxIN must be connected to VIN to ensure proper device operation", in Table 53, Type 1 Buck regulator electrical characteristic.

6. Add note: "VSW7IN must be connected to VIN to ensure proper operation", in Table 60, Type 2 Buck regulator electrical characteristic.

7. Add note: "Input supply for switching regulators must be capable to sink current to avoid overvoltage condition during the power down sequence of the device", in Table 9, Power tree summary.

Revision 9.0: PF8100_PF8200 Data Sheet Change Summary

1. Add new line to clarify SW5 Peak current limit specification, Table 53: Type 1 buck regulator electrical characteristics.

Symbol: ISW5LIM

Parameter: Current limiter - inductor peak current detection SWxLIM[1:0] = 11

Min value 3.9 A / Typ value 4.5 A / Max value 5.45 A

2. Add note: "Current limit applicable to SW5 to ensure maximum power requirement for the MEMC rail in i.MX8QM systems", in Table 53, Type 1 Buck regulator electrical characteristic.

3. Add note: "Current limit applicable to SW1, SW2, SW3, SW4, and SW6", in Table 53, Type 1 Buck regulator electrical characteristic.

4. Divide Section 14.9.11 content into two subtopics to clarify FSOB configuration differences between PF8200 and PF8100 devices.

The PF8100-PF8200 revision 9.0 data sheet (including revision 8.0) is attached to this notice and is available at: https://www.nxp.com/docs/en/data-sheet/PF8100_PF8200.pdf

Corresponding ZVEI Delta Qualification Matrix ID: SEM-DS-02, SEM-DS-03

Reason

Revision 8.0 data sheet has been updated to accommodate sequence options for expanded selection of memory options, and to include clarification notes for regulator electrical characteristics tables.

Revision 9.0 data sheet has been updated to expand parameter ISW5LIM details to ensure clarity and compatibility with the i.MX8QM microprocessors specification, as well as clarify the FSOB configuration differences between PF8100 and PF8200 devices.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Data Sheet Revision

A new datasheet will be issued

Additional information

Affected products and sales history information: see attached file

Additional documents: [view online](#)



Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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